



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: KELKAR et al.

Application No.: 09/653,925

Filed: September 1, 2000

Title: WAFER LEVEL CHIP SCALE PACKAGE

Attorney Docket No.:

NSC1P181/P04767

Examiner: Parekh, N.

Group: 2811

#10/B
2/11/03
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I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail to: Assistant Commissioner for Patents, Washington, DC 20231 on January 31, 2003.

Printed Name: Tara Hayden

Signed: 

AMENDMENT B

Assistant Commissioner for Patents
Washington, D.C. 20231

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Dear Sir:

In response to the Office Action dated 31 October 2002, please amend the above-identified patent application and consider the remarks as follows.

IN THE CLAIMS:

Please CANCEL claims 23, 24, 27, and 28 without prejudice or disclaimer.

Please REWRITE claims 1 and 15 as follows: